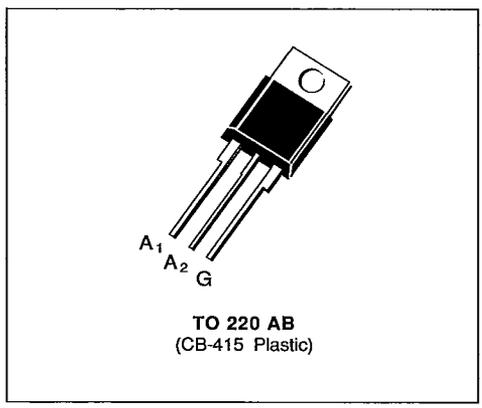


**SNUBBERLESS TRIACS**

- $I_{TRMS} = 6 \text{ A}$  at  $T_c = 95^\circ\text{C}$ .
- $V_{DRM} : 200 \text{ V}$  to  $800 \text{ V}$ .
- $I_{GT} = 50 \text{ mA}$  (QI-II-III).
- GLASS PASSIVATED CHIP.
- HIGH SURGE CURRENT :  $I_{TSM} = 60 \text{ A}$ .
- HIGH COMMUTATION CAPABILITY :  
 $(di/dt)_c > 5 \text{ A / ms}$  without snubber.
- INSULATING VOLTAGE :  $2500 \text{ V}_{RMS}$ .



**DESCRIPTION**

**ABSOLUTE RATINGS** (limiting values)

Symbol	Parameter		Value	Unit
$I_{TRMS}$	RMS on-state current (360 ° conduction angle)	$T_c = 95^\circ\text{C}$	6	A
$I_{TSM}$	Non repetitive surge peak on-state current ( $T_j$ initial = $25^\circ\text{C}$ )	$t = 8.3 \text{ ms}$	63	A
		$t = 10 \text{ ms}$	60	
$I^2 t$	$I^2 t$ value	$t = 10 \text{ ms}$	18	$\text{A}^2 \text{ s}$
$di/dt$	Critical rate of rise of on-state current (1)	Repetitive $F = 50 \text{ Hz}$	20	A / $\mu\text{s}$
		Non Repetitive	100	
$T_{stg}$ $T_j$	Storage and operating junction temperature range		- 40, + 150	$^\circ\text{C}$
			- 40, + 125	$^\circ\text{C}$

Symbol	Parameter	BTA 06-					Unit
		200 BW	400 BW	600 BW	700 BW	800 BW	
$V_{DRM}$	Repetitive peak off-state voltage (2)	$\pm 200$	$\pm 400$	$\pm 600$	$\pm 700$	$\pm 800$	V

(1) Gate supply :  $I_G = 500 \text{ mA} - di_G / dt = 1 \text{ A / } \mu\text{s}$ .  
 (2)  $T_j = 125^\circ\text{C}$ .

**THERMAL RESISTANCES**

Symbol	Parameter	Value	Unit
$R_{th(j-a)}$	Junction to ambient	60	°C/W
$R_{th(j-c)} DC$	Junction to case for DC	4.3	°C/W
$R_{th(j-c)} AC$	Junction to case for 360° conduction angle (F = 50 Hz)	3.2	°C/W

**GATE CHARACTERISTICS (maximum values)**

$P_{GM} = 40 W$  (t = 10  $\mu s$ )    $P_{G(AV)} = 1 W$     $I_{GM} = 4 A$  (t = 10  $\mu s$ )    $V_{GM} = 16 V$  (t = 10  $\mu s$ ).

**ELECTRICAL CHARACTERISTICS**

Symbol	Test Conditions	Quadrants	Min.	Typ.	Max.	Unit
$I_{GT}$	$T_j = 25\text{ °C}$ $V_D = 12\text{ V}$ Pulse duration > 20 $\mu s$ $R_L = 33\ \Omega$	I-II-III	2		50	mA
$V_{GT}$	$T_j = 25\text{ °C}$ $V_D = 12\text{ V}$ Pulse duration > 20 $\mu s$ $R_L = 33\ \Omega$	I-II-III			1.5	V
$V_{GD}$	$T_j = 125\text{ °C}$ $V_D = V_{DRM}$ Pulse duration > 20 $\mu s$ $R_L = 3.3\text{ k}\Omega$	I-II-III	0.2			V
$I_H^*$	$T_j = 25\text{ °C}$ $I_T = 100\text{ mA}$ Gate open $R_L = 140\ \Omega$				50	mA
$I_L$	$T_j = 25\text{ °C}$ $V_D = 12\text{ V}$ Pulse duration > 20 $\mu s$ $I_G = 500\text{ mA}$	I-III		50		mA
		II		100		
$V_{TM}^*$	$T_j = 25\text{ °C}$ $I_{TM} = 8.5\text{ A}$ $t_p = 10\text{ ms}$				1.75	V
$I_{DRM}^*$	$T_j = 25\text{ °C}$ $T_j = 125\text{ °C}$ $V_{DRM}$ rated   Gate open				0.01	mA
					2	
$dv/dt^*$	$T_j = 125\text{ °C}$ Gate open Linear slope up to 0.67 $V_{DRM}$		500	750		V/ $\mu s$
$(di/dt)_c^*$	$T_j = 125\text{ °C}$ $V_{DRM}$ rated Without snubber		5	10		A/ms
$t_{gt}$	$T_j = 25\text{ °C}$ $di_G/dt = 3.5\text{ A}/\mu s$ $I_G = 500\text{ mA}$ $I_T = 8.5\text{ A}$ $V_D = V_{DRM}$	I-II-III		2		$\mu s$

\* For either polarity of electrode A<sub>2</sub> voltage with reference to electrode A<sub>1</sub>.

# SGS-THOMSON

# T-25-15

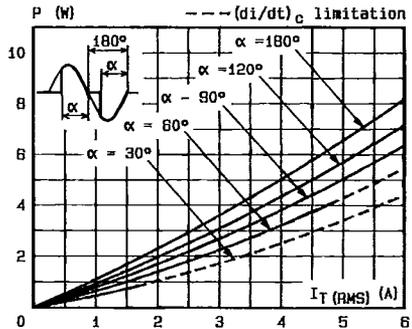


Fig. 1 - Maximum mean power dissipation versus RMS on-state current (F = 60 Hz).

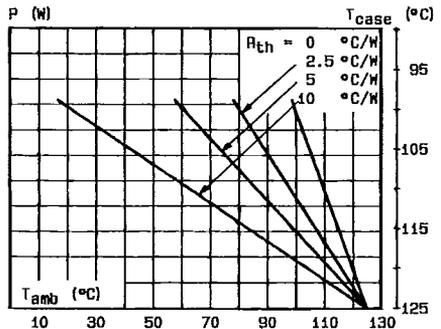


Fig. 2 - Correlation between maximum mean power dissipation and maximum allowable temperatures (T\_amb and T\_case) for different thermal resistances heatsink + contact.

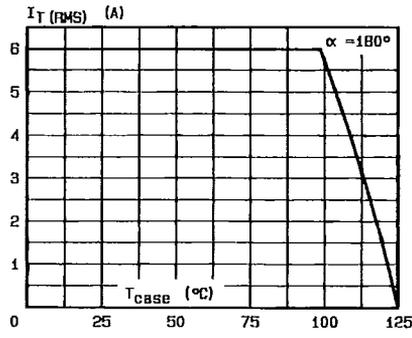


Fig. 3 - RMS on-state current versus case temperature.

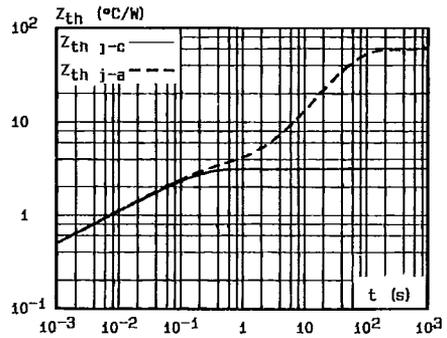


Fig. 4 - Thermal transient impedance junction to case and junction to ambient versus pulse duration.

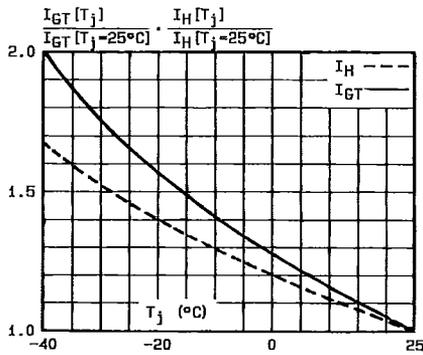


Fig. 5 - Relative variation of gate trigger current and holding current versus junction temperature.

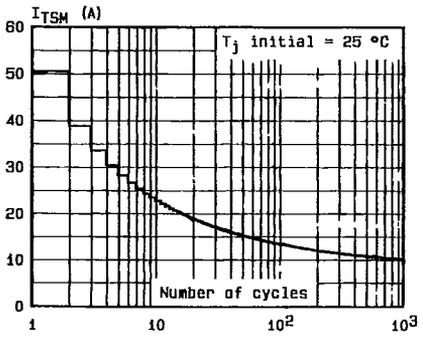


Fig. 6 - Non repetitive surge peak on-state current versus number of cycles.



